



APPLICATION	PASTE DESCRIPTION	VISCOSITY	VOLUME RESISTIVITY ( $\mu\text{Ohms-cm}$ )	THERMAL CONDUCTIVITY (W/mK)	APPLICATION PROCESS	SINTERING PROCESS
Via Fill and Z-Axis Interconnection	<a href="#">Ormet 701</a> ::: <a href="#">MSDS</a> ::: Ormet 701 is a lead-free conductive paste used to fill micro via structures that create z-axis interconnections between circuit layers in semiconductor packaging and printed circuit boards.	Included on Data Sheet	50	25	Flood Fill	Lamination Press
	<a href="#">Ormet 702</a> ::: <a href="#">MSDS</a> ::: A no slump Cu-sintering paste used to form Z-axis-interconnects by printing bumps that pass through clearance holes in a b-staged adhesive.	Included on Data Sheet	50	25	Stencil Print / Dispense	Lamination Press
	<a href="#">Ormet 710</a> ::: <a href="#">MSDS</a> ::: A high-metal-loading Cu-sintering paste used to form Z-axis interconnects by filling through or blind microvia in multilayer boards and substrates.	Included on Data Sheet	30	25	Stencil Print	Lamination Press
Conductive Lines and Traces.	<a href="#">Ormet 265</a> ::: <a href="#">MSDS</a> ::: A Cu-sintering paste used for creating circuit traces. Formulated to adhere to non-metallic surfaces.	Included on Data Sheet	40	25	Screen Print / Dispense	Lamination press, N2 reflow, or box oven with nitrogen
	<a href="#">Ormet 270</a> ::: <a href="#">MSDS</a> ::: A Cu-sintering paste used for creating circuit traces on a b-staged adhesive layer. The Ormet material co-processes with the b-stage layer to form a strong adhesive bond	Included on Data Sheet	50	25	Screen Print	Lamination press, N2 reflow, or box oven with nitrogen
Semiconductor Die Attach.	<a href="#">...</a> ::: <a href="#">...</a> ::: Ormet has developed a unique high thermally conductive Pb free die attach paste that forms an intermetallic bond between the die backside and substrate. The metallic bond provides high adhesion at elevated temperatures on a variety of surfaces, including Ag, Au, PPF, and bare Cu. Ormet's die attachment paste properties make it an excellent candidate to replace Ag filled epoxy and solders used in power TO, SO, QFN, Clip QFN and SiP packages. Please contact us for a product recommendation for your specific application.	Included on Data Sheet	<100	20-40	Dispense and Stencil Print	Standard Pb-free reflow with a 2 minute soak @260C peak temperature, or box oven cure. Note: Requires O2 levels below 500ppm
Component Attach.	<a href="#">Presentation</a> ::: <a href="#">Ormet 400</a> ::: <a href="#">MSDS</a> ::: A screen printable, Lead-free sintering paste used as an alternative to solder paste.	Included on Data Sheet	35	45	Stencil Print	Reflow furnace with nitrogen atmosphere
	<a href="#">Ormet 406</a> ::: <a href="#">MSDS</a> ::: A finer pitch and dispensable version of Ormet 400.	Included on Data Sheet	35	45	Stencil or dispense	Reflow furnace or box oven with nitrogen atmosphere
PTH Fill.	<a href="#">Presentation</a> ::: <a href="#">Ormet 805</a> ::: <a href="#">MSDS</a> ::: A Cu-sintering paste used for plugging thermal vias and copper through holes.	Included on Data Sheet	35	50	Pneumatic Pressure Fill	Lamination Press, Autoclave or

